LN2162C68TR

Surface Mounting Chip LED

GW Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25$ °C

• Pure Green

Parameter	Symbol	Rating	Unit	
Power dissipation	P_{D}	45	mW	
Forward current	I_{F}	15	mA	
Pulse forward current *	I_{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	√° C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Orange

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Power dissipation	P _D	45	mW
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Pulse forward current *	I_{FP}	60	mA
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Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics T_a = 25°C

• Pure Green

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		1.2	2.5		mcd
Forward current	CI _f			10		mA
Forward voltage	V_{F}	$I_F = 10 \text{ mA}$		2.05	2.8	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		555		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		25		nm
Reverse current	I_R	$V_R = 3 V$			10	μΑ

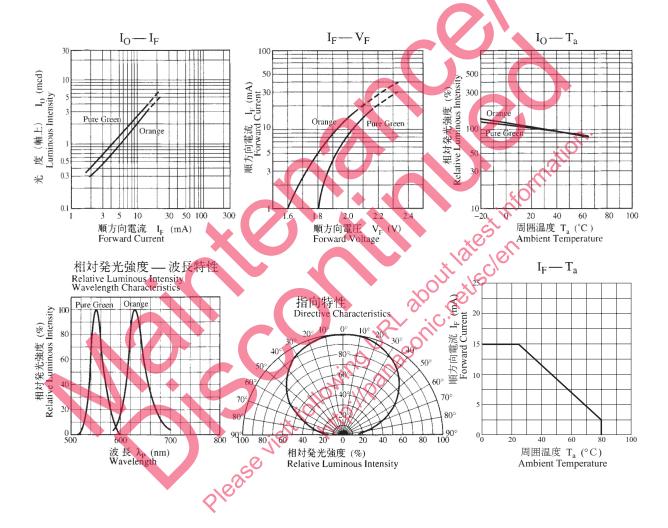
■ Lighting Color / Lens Color

- Pure Green / Clear
- Orange / Clear

■ Electro-Optical Characteristics (Continued) $T_a = 25$ °C

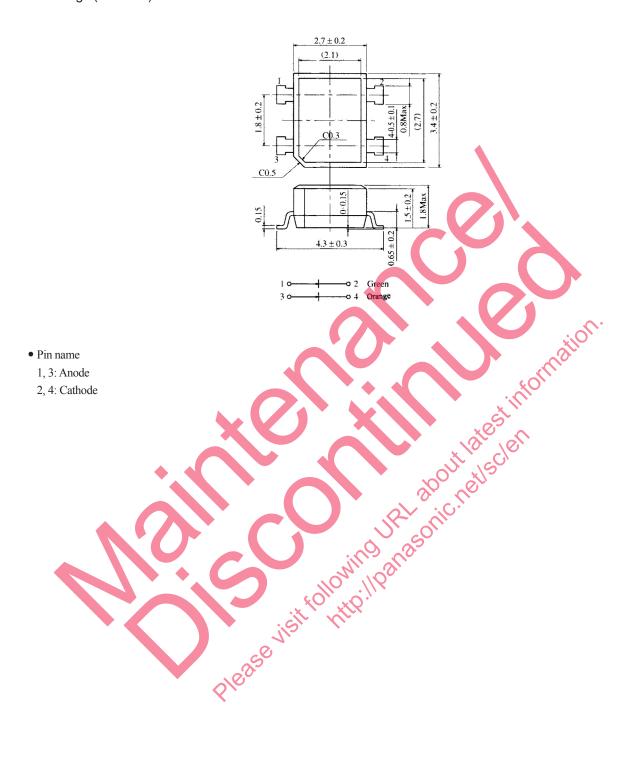
• Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		0.8	2.1		mcd
Forward current	I_F			10		mA
Forward voltage	V _F	$I_F = 10 \text{ mA}$		1.95	2.8	V
Peak emission wavelength	$\lambda_{ m P}$	$I_F = 10 \text{ mA}$		630		nm
Spectral half band width	Δλ	$I_F = 10 \text{ mA}$		40		nm
Reverse current	I_R	$V_R = 3 V$			10	μΑ



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■ Package (Unit: mm)



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